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## KOREAN PATENT ABSTRACTS

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(54) SEMICONDUCTOR PACKAGE BUMP, CONNECTING METHOD BETWEEN BUMP AND COPPER CIRCUIT PATTERN, AND BUMP STRUCTURE OF SEMICONDUCTOR PACKAGE FOR THE SAME

(57) Abstract:

PURPOSE: A semiconductor package bump, a connecting method between the bump and a copper circuit pattern, and a bump structure of a semiconductor package for the same are provided to be capable of improving the contact reliability between the bump and the copper circuit pattern and preventing delamination phenomenon.

CONSTITUTION: A copper circuit pattern(94) is formed at the upper portion of a substrate(93), wherein the copper circuit pattern is partially bent. The center portion of the bent copper circuit pattern contacts at least one side edge portion of a bump(91) of a semiconductor package. Preferably, the bump formed at the back side of the semiconductor package, includes a normal part, wherein the normal part contacts the copper thin circuit pattern of the substrate.



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